



HC6912

60V N-Channel MOSFET

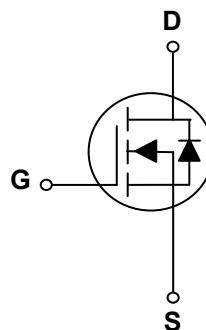
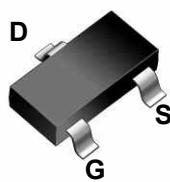
General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

Features

V_{DS}	60V
I_D (at $V_{GS}=10V$)	3.0A
$R_{DS(ON)}$ (at $V_{GS}=10V$)	85mΩ(Typ)

SOT23



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D (TC=25°C)	3.0	A
	I_D (TC=100°C)	1.8	A
Drain Current – Pulsed	I_{DM}	12	A
Maximum Power Dissipation	P_D	1.56	W
Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	°C
Thermal Characteristics			
Parameter	Symbol	Typ	Max
Thermal Resistance junction-case	$R_{\theta JC}$		80
Thermal Resistance junction-to-Ambient	$R_{\theta JA}$		125

Electrical Characteristics (TJ=25°C unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	60			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=60V, V_{GS}=0V$			1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$			± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	0.9	1.3	2.0	V
$R_{DS(ON)}$	Drain-Source On-State-Resistance	$V_{GS}=10V, I_D=3A$		85	100	$m\Omega$
		$V_{GS}=4.5V, I_D=2A$		90	120	$m\Omega$
g_{fs}	Forward Transconductance	$V_{DS}=10V, I_D=3A$		7		S
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{DS}=15V, V_{GS}=0V,$ $F=1.0MHz$		409		pF
C_{oss}	Output Capacitance			45		pF
C_{rss}	Reverse Transfer Capacitance			40		pF
SWITCHING PARAMETERS						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=30V, I_D=1A,$ $V_{GS}=10V,$ $R_G=3.3\Omega$		2.9		nS
t_r	Turn-on Rise Time			9.5		nS
$t_{d(off)}$	Turn-Off Delay Time			18.4		nS
t_f	Turn-Off Fall Time			5.3		nS
Q_g	Total Gate Charge	$V_{DS}=48V, I_D=6A,$ $V_{GS}=10V$		9.3		nC
Q_{gs}	Gate-Source Charge			2.1		nC
Q_{gd}	Gate-Drain Charge			1.8		nC
V_{SD}	Diode Forward Voltage	$V_{GS}=0V, I_s=1A$		0.70	1.4	V

Note:

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

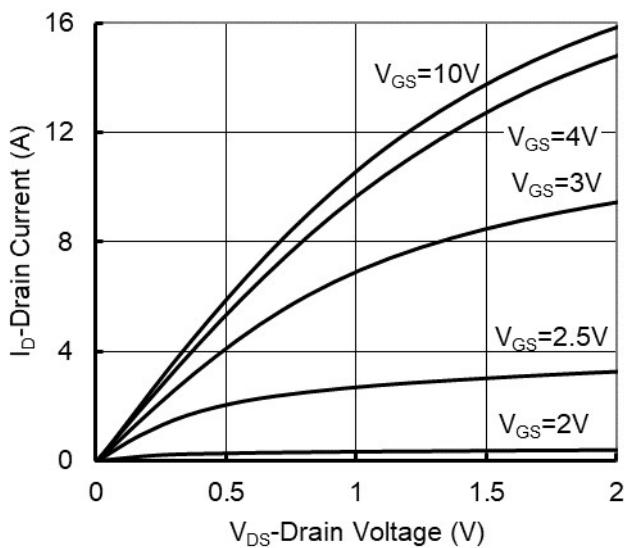


Figure 1. Output Characteristics

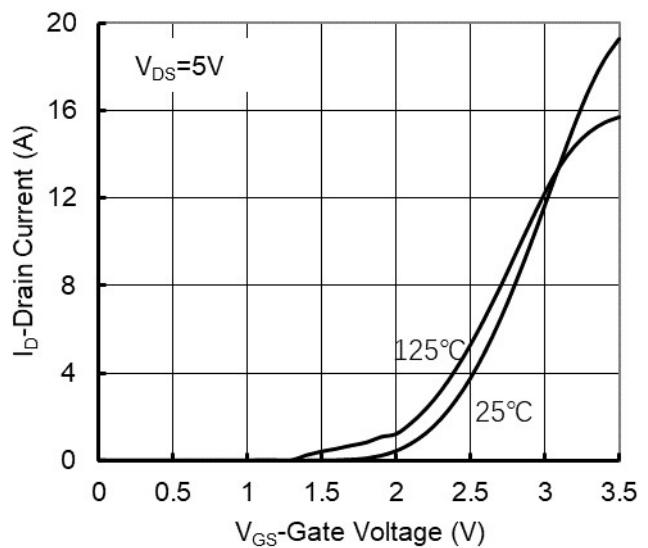


Figure 2. Transfer Characteristics

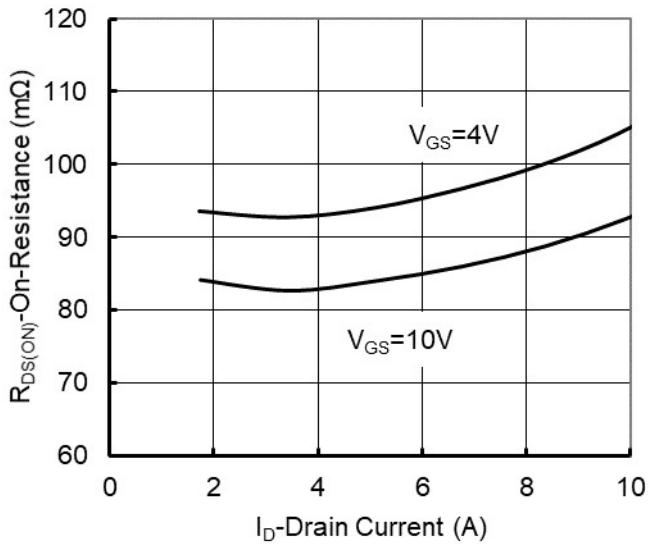


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

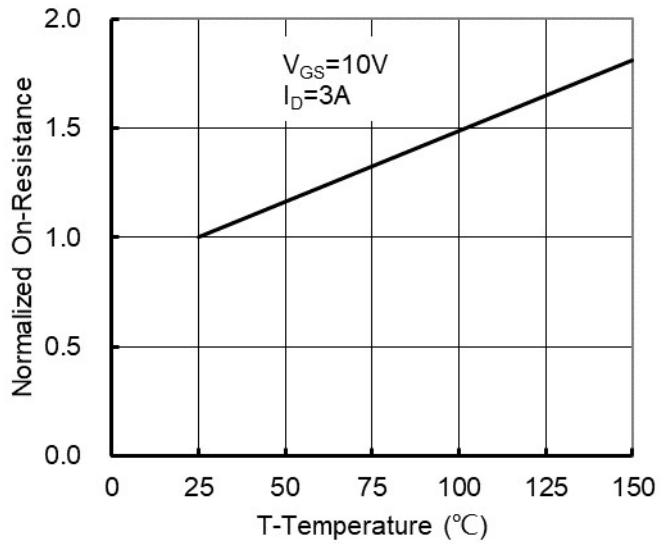


Figure 4: On-Resistance vs. Junction Temperature

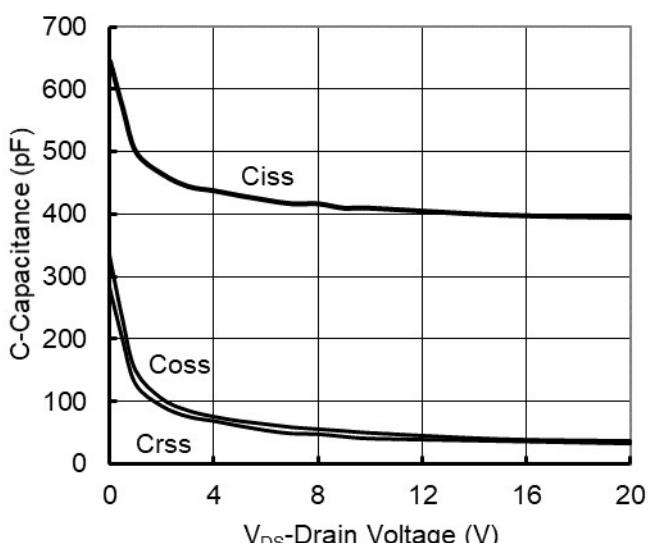


Figure 5. Capacitance Characteristics

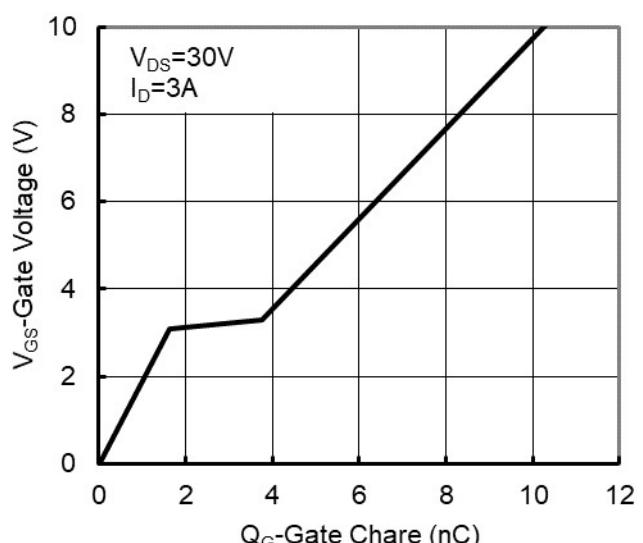


Figure 6. Gate Charge

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

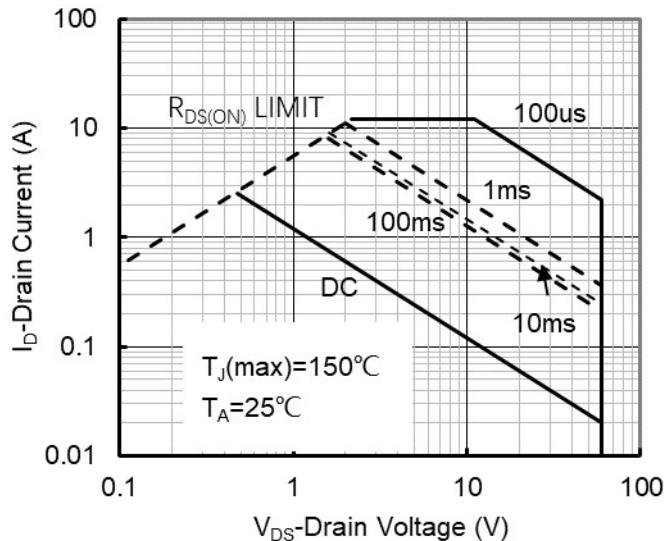


Figure 7. Safe Operation Area

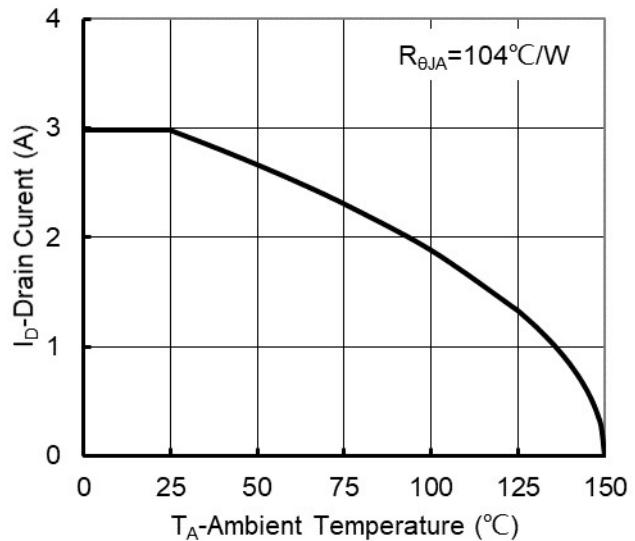


Figure 8. Maximum Continuous Drain Current vs Ambient Temperature

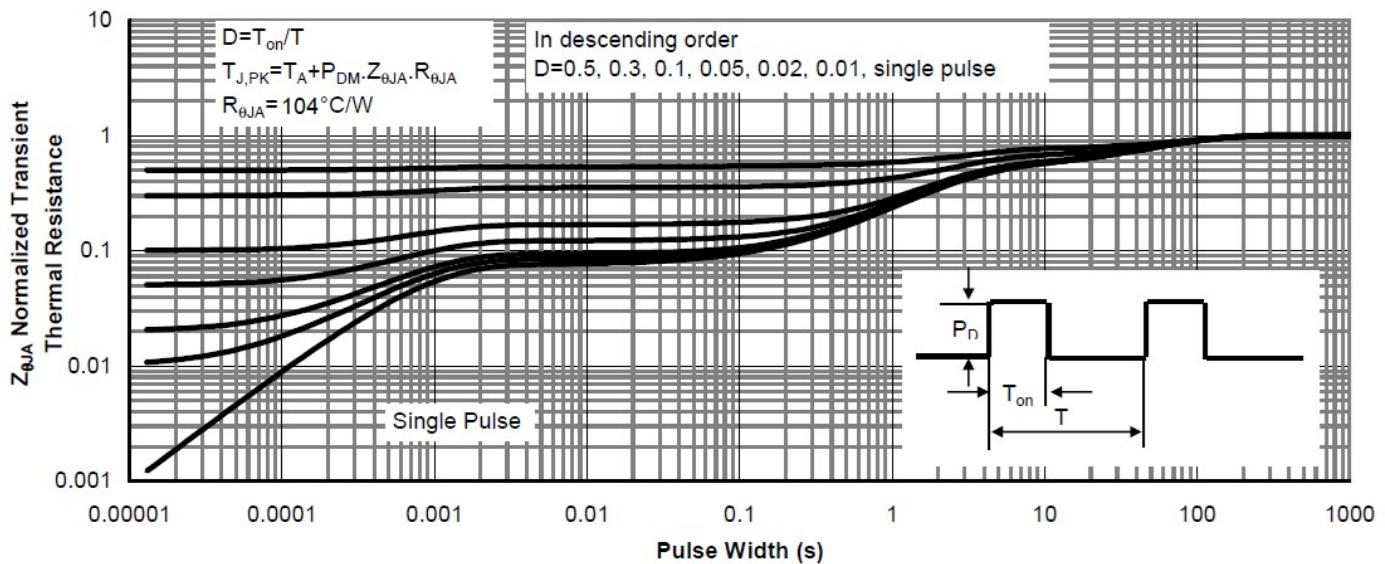
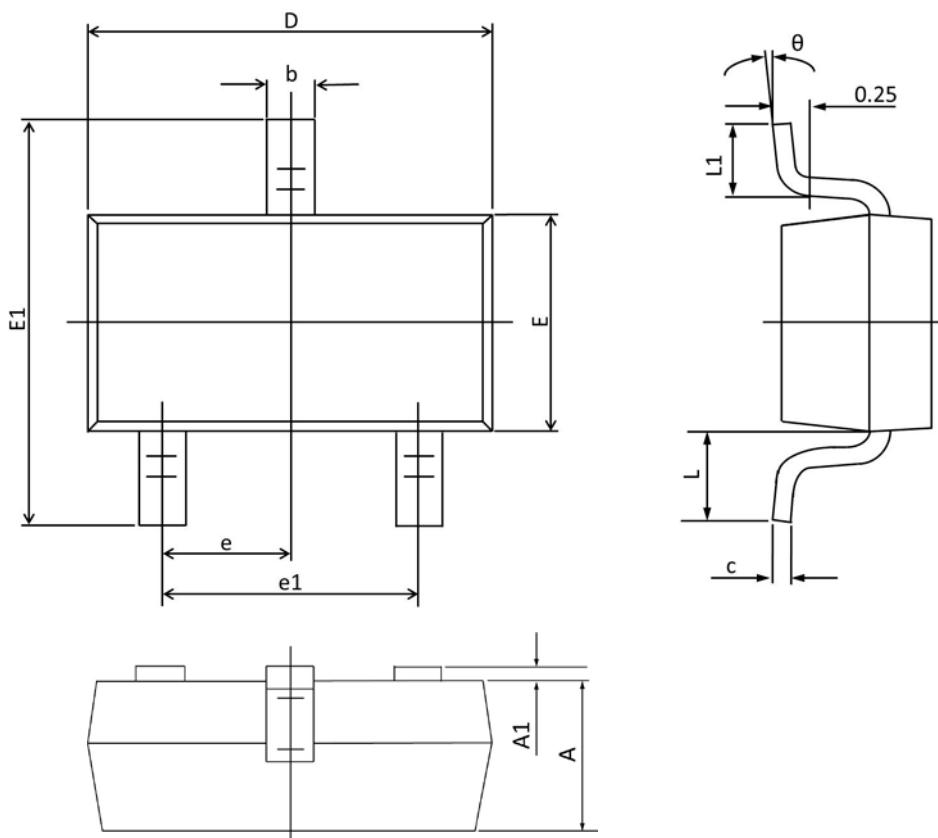


Figure 9. Normalized Maximum Transient Thermal Impedance

SOT23 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.000	0.035	0.039
A1	0.000	0.100	0.000	0.004
b	0.300	0.500	0.012	0.020
c	0.090	0.110	0.003	0.004
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
θ	1°	7°	1°	7°